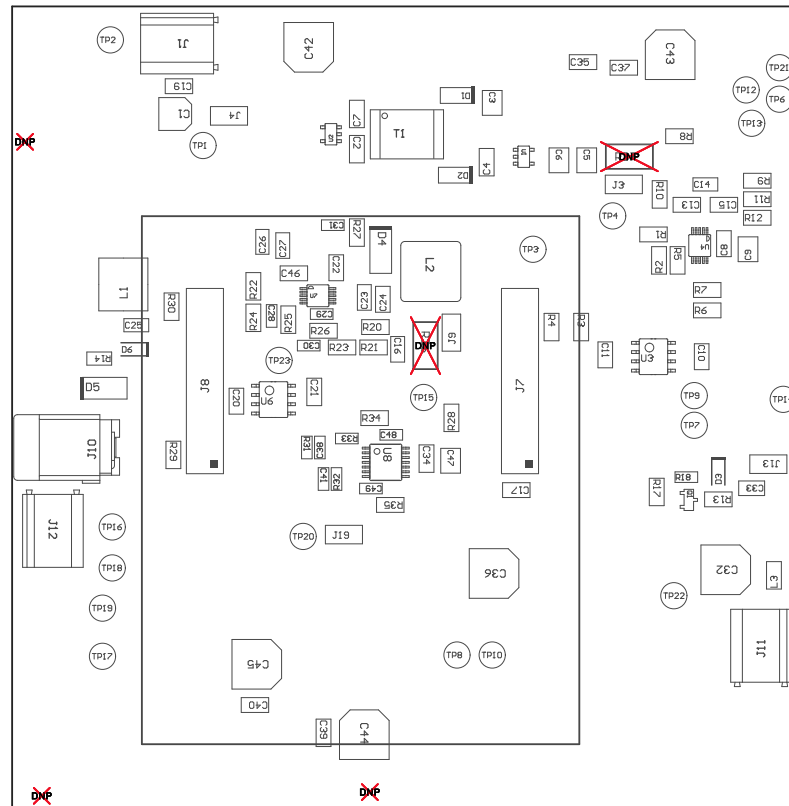
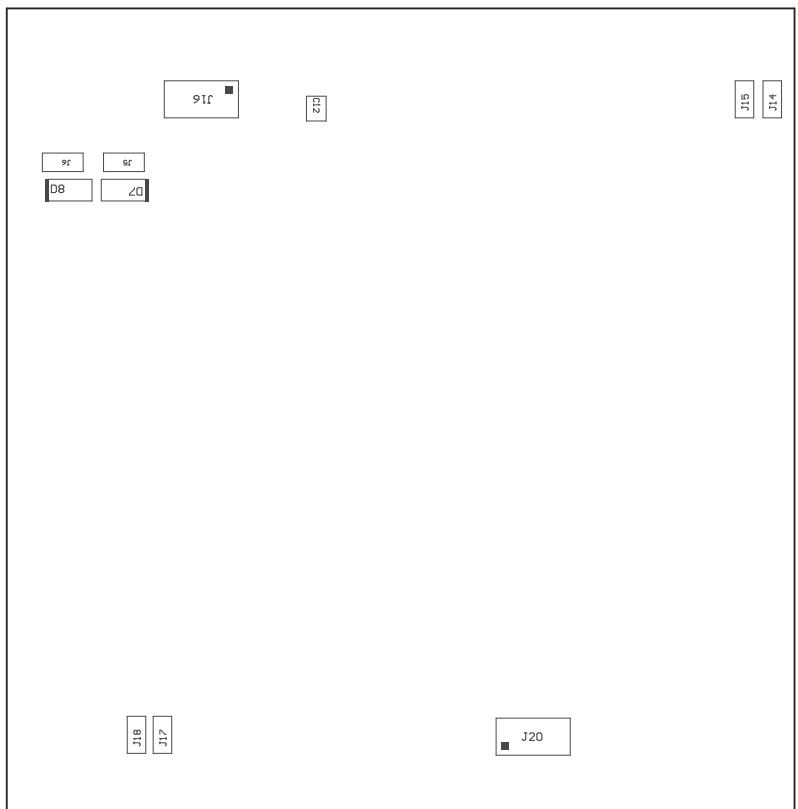


Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: TIDA-00794 | REV: E1 | SUN REV: Not In VersionControl |
| | TID #: TIDA-00794 | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 3/23/2016 4:56:40 PM | TEXAS INSTRUMENTS | |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

| | | | |
|-------------------------------------|----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: TIDA-00794 | REV: E1 | SUN REV: Not In VersionControl |
| | TID #: TIDA-00794 | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 3/23/2016 4:56:43 PM | TEXAS INSTRUMENTS | |

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